

# MicroTech 2021 Annual Online Conference

## “Heterogeneous Integration”

# CALL FOR ABSTRACTS



## Online Conference – 25<sup>th</sup> March 2021

**MicroTech 2021** is the **Annual IMAPS-UK Conference** which, this year, focuses on key emerging markets and their associated technological challenges associated with **Heterogeneous Integration – Packaging Future Microsystems**. This **Online Conference** combines invited Keynotes, presentations and posters from leading companies and academic institutions.

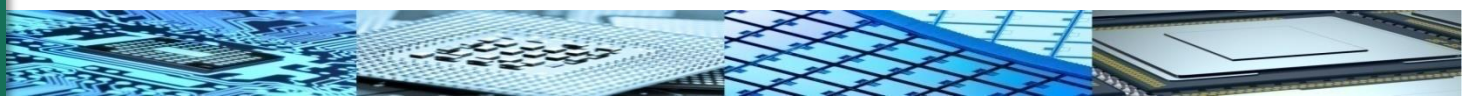
This event will present an insight into the world of **Heterogeneous Integration (HI) for the Microelectronics** community. The IEEE have recently published the roadmap for HI as series of 23 chapters covering applications, materials, processes and other related topics. As HI covers such a wide range of technologies, MicroTech 2021 will provide a look at the key issues and developments that will affect microelectronic packaging research and development in both industry and academia in the near future.

IMAPS-UK invites **Abstracts** which describe the latest advancements in **package design, materials, next-level-integration and performance** while maintaining **reliability, sustainability and manufacturability**.

**MicroTech 2021** aims to provide the **Online Delegates** with an opportunity to learn from and network with **leading Industry Experts** as they share their experiences, developments and opportunities.

### Organising Committee

<b>Event Chair:</b>	Andy Longford, Panda Europe	
<b>Technical Committee:</b>	David King, Carolyn Short Andrew Holland, Scott Wood	<b>Secretariat:</b> Steve Riches





## Instructions for participation

We invite submission of abstracts in the following areas:

**Research and Development Papers:** These will describe high-impact academic research relating to the conference topics.

**Technical Presentations:** Technical presentations showcasing in-production or pre-production techniques relating to the conference topics.

**Current/Future trends:** Presentations demonstrating how markets related to the main conference topics are developing over time.

All abstracts received by the submission deadline will be evaluated by the technical committee. Abstracts covering a balanced range of the main conference topics will be selected and invited to provide an **Oral Presentation** (15mins + 5 mins questions) or **Video Presentation** (5 mins) during the online conference.

# Conference Topics – Heterogenous Integration

Markets and Developments	Integration	Materials	Design and Test
<ul style="list-style-type: none"> <li>• High Performance Computing</li> <li>• Internet of Things (IoT)</li> <li>• Automotive</li> <li>• Aerospace and Defence</li> <li>• Mobile</li> </ul>	<ul style="list-style-type: none"> <li>• Single chip and multi-chip</li> <li>• Photonics</li> <li>• Power Electronics</li> <li>• MEMS and Sensor</li> <li>• 5G</li> <li>• SiP and Module System</li> </ul>	<ul style="list-style-type: none"> <li>• Emerging Research materials</li> <li>• Emerging Devices</li> <li>• Thermal Management</li> <li>• Wafer Level Packaging</li> <li>• Interconnects for 2D and 3D architectures</li> </ul>	<ul style="list-style-type: none"> <li>• Co-Design</li> <li>• Modelling and Simulation</li> <li>• Test Technology</li> <li>• Security</li> </ul>

Those wishing to present their work at MicroTech2021 should submit an abstract of approximately 200 words, electronically to: [office@imaps.org.uk](mailto:office@imaps.org.uk)

## Deadlines

Abstract submission (200-300 words)	Friday 18 <sup>th</sup> December 2020
Acceptance of Abstracts for Oral and Video Presentation	Friday 22 <sup>nd</sup> January 2021
Confirmed speaker biographies and photographs	Friday 26 <sup>th</sup> Feb 2021
Final slide set or video (ppt/pdf/mp4)	Friday 19 <sup>th</sup> Mar 2021